CRMKEL1050A

P-Channel -100V, 36mΩ Typ. Power MOSFET

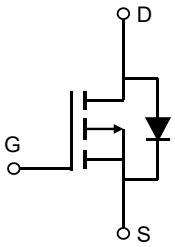
Description

Features

- -100V, -35A

  $R_{DS(ON)}$ Typ = 36mΩ @ V_{GS} = -10V

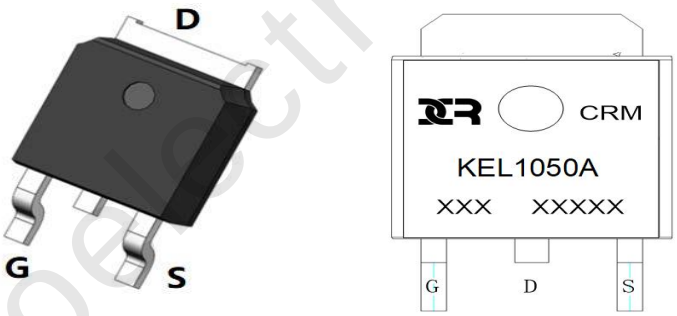
  $R_{DS(ON)}$ Typ = 45mΩ @ V_{GS} = -4.5V
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKEL1050A	CRMKEL1050A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		-100	V
V_{GS}	Gate-to-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25°C	-35	A
		T_C = 100°C	-21	A
I_{DM}	Pulsed Drain Current [1]		-140	A
E_{AS}	Single Pulsed Avalanche Energy [2]		110	mJ
P_D	Power Dissipation	T_C = 25°C	104	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.2	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	-100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -80V, V_{GS} = 0V	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250μA	-1.4	-2	-2.6	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(3)	V_{GS} = -10V, I_D = -12A	-	36	47	mΩ
		V_{GS} = -4.5V, I_D = -8A	-	45	59	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = -25V, f = 1MHz	-	1230	-	pF
C_{oss}	Output Capacitance		-	620	-	pF
C_{rss}	Reverse Transfer Capacitance		-	44	-	pF
Q_g	Total Gate Charge	V_{GS} = 0 to -10V, V_{DS} = -50V, I_D = -15A	-	19	-	nC
Q_{gs}	Gate Source Charge		-	7	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = -10V, V_{DD} = -50V, I_D= -15A, R_{GEN} = 6Ω	-	12	-	ns
t_r	Turn-On Rise Time		-	55	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	40	-	ns
t_f	Turn-Off Fall Time		-	75	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-35	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-140	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S = -12A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I_F = -15A, di/dt = 100A/us	-	50	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	125	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25°C, V_{DD}=-50V, V_G=-10V, R_G=25ohm, L=0.5mH, I_{AS}=-21A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit

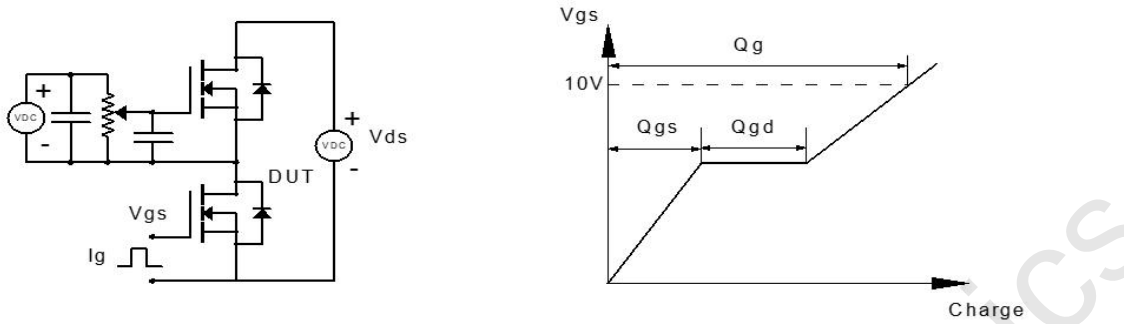


Figure 1: Gate Charge Test Circuit & Waveform

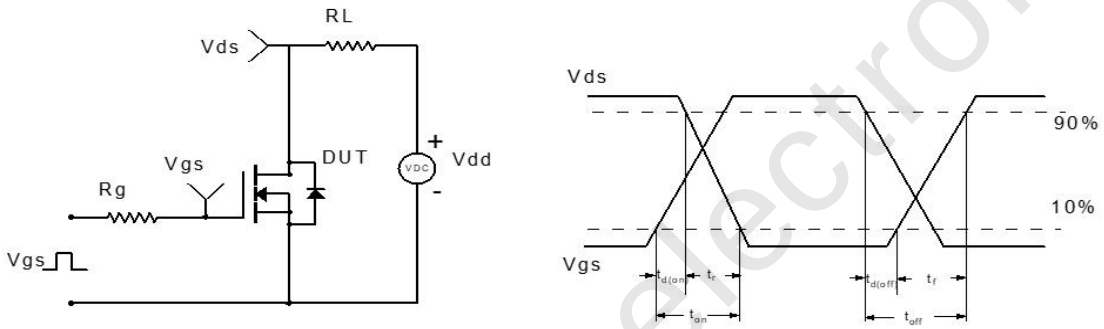


Figure 2: Resistive Switching Test Circuit & Waveform

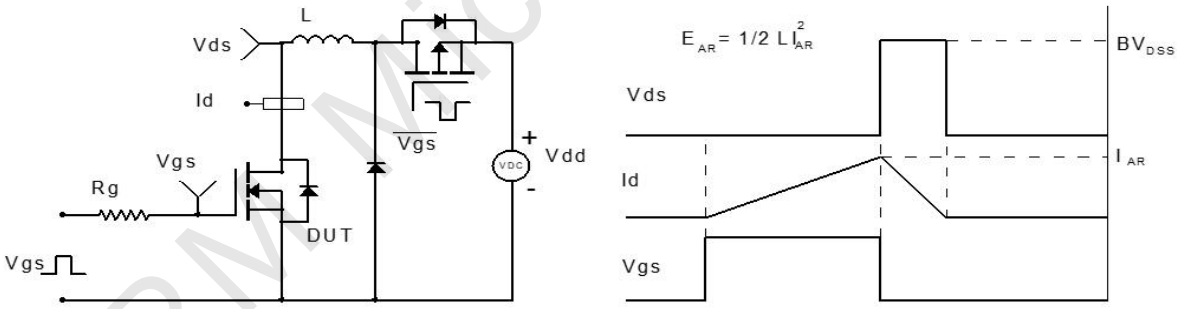


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

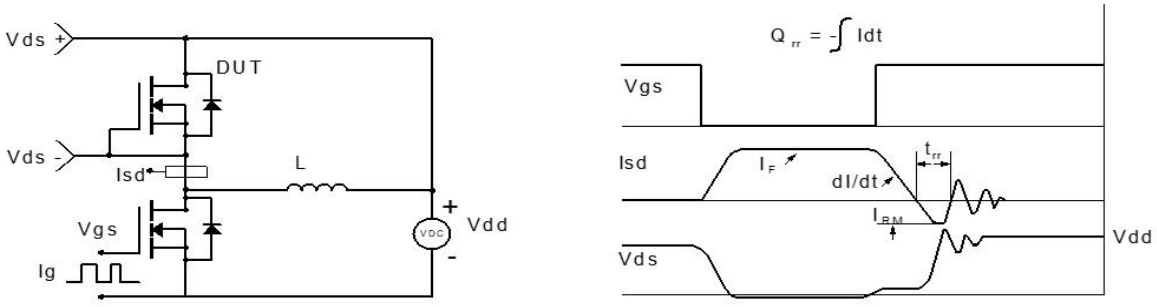
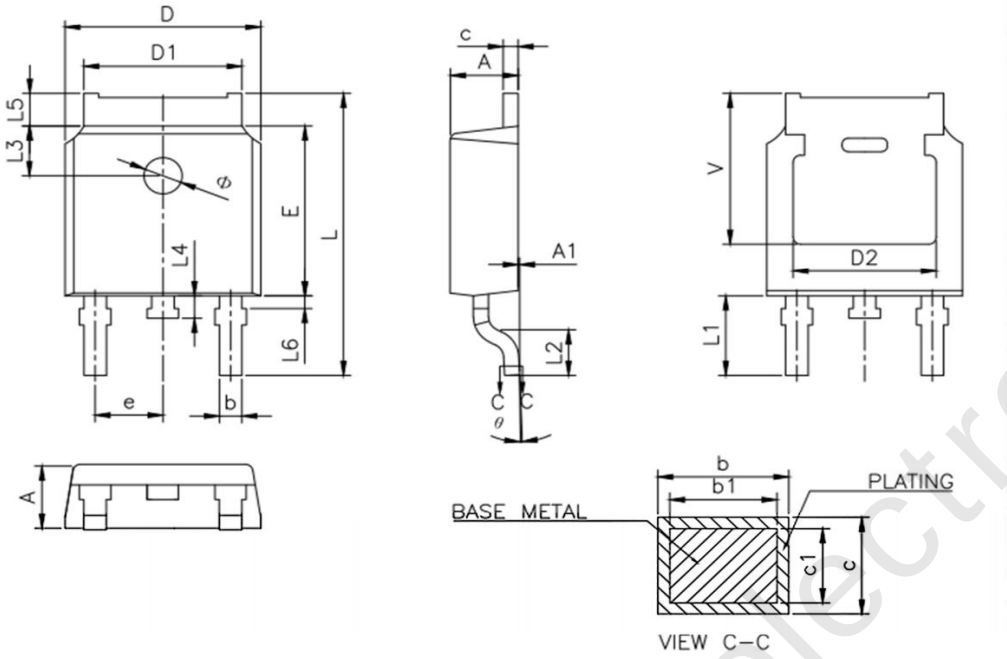


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	--	0.127
b	0.66	--	0.86
b1	0.65	0.76	0.81
D	6.50	6.60	6.70
D1	5.10	5.33	5.46
c	0.47	--	0.60
c1	0.46	0.51	0.56
D2	4.83 REF.		
E	6.00	6.10	6.20
e	2.186	2.286	2.386
L	9.80	10.10	10.40
L1	2.90 REF.		
L2	1.40	1.50	1.60
L3	1.80 REF.		
L4	0.60	0.80	1.00
L5	0.90	--	1.25
L6	0.15	--	0.75
Φ	1.10	--	1.30
θ	0°	--	8°
V	5.40 REF		

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